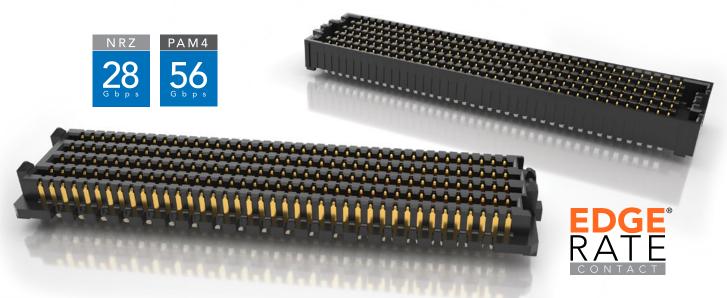


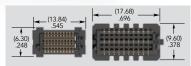
ULTRA HIGH-DENSITY, HIGH-SPEED OPEN-PIN-FIELD ARRAYS

(0.80 mm) .0315" PITCH



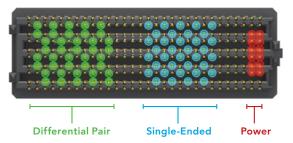
FEATURES & BENEFITS

- 0.80 mm (.0315") pitch grid
- 50% board space savings versus .050" (1.27 mm) pitch arrays
- Performance up to 28 Gbps NRZ/56 Gbps PAM4
- Rugged Edge Rate® contact system
- Up to 500 I/Os
- 7 mm and 10 mm stack heights
- Solder charge terminations for ease of processing
- Lower insertion/withdrawal forces



0.80 mm pitch vs. 1.27 mm pitch (60 pins shown)

MAXIMUM GROUNDING & ROUTING FLEXIBILITY



KEY SPECIFICATIONS

PITCH	STACK HEIGHTS	TOTAL PINS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	CURRENT RATING	LEAD-FREE SOLDERABLE
0.80 mm	7 mm & 10 mm	up to 500 I/Os	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	1.3 A per pin (10 adjacent pins powered)	Yes

Due to technical progress, all designs, specifications and components are subject to change without notice.





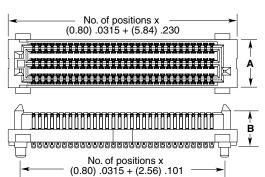


(0.80 mm) .0315" PITCH • ULTRA HIGH-DENSITY ARRAYS



A-SEAM8 Board Mates: A-SEAF8





NO. OF ROWS	A	
-04	(4.30) .169	
-06	(6.30) .248	
-08	(8.30) .327	

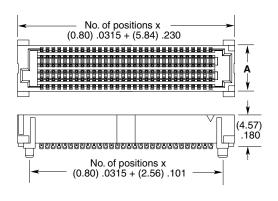
LEAD STYLE	В	
-S02.0	(4.54) .179	
-S05.0	(7.54) .297	

MA	MATED HEIGHTS*				
A-SEAF8	A-SEAM8 LEAD STYLE				
LEAD STYLE	-S02.0	-S05.0			
-05.0	(7.00).276	(10.00) .394			

^{*}Processing conditions will affect mated height.

A-SEAF8 Board Mates: A-SEAM8





Due to technical progress, all designs, specifications and components are subject to change without notice.

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SEAM8-30-S05.0-STL-06-1